



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20250902000.2

**Qualification of TI Philippines (PHI) as an additional Assembly & Test
site for select package devices
Change Notification / Sample Request**

Date: September 03, 2025

To: Mouser PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team
SC Business Services

20250902000.2
Change Notification / Sample Request
Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
INA186A1QDBVRQ1	NULL
INA186A3QDBVRQ1	NULL
INA186A2QDBVRQ1	NULL

Technical details of this Product Change follow on the next page(s).

PCN Number:	20250902000.2			PCN Date:	September 03, 2025		
Title:	Qualification of TI Philippines (PHI) as an additional Assembly & Test site for select package devices						
Customer Contact:	Change Management team		Dept:	Quality Services			
Proposed 1st Ship Date:	March 02, 2026		Estimated Sample Availability:	November 02, 2025			
*Sample requests received after November 02, 2025 will not be supported.							
Change Type:							
<input checked="" type="checkbox"/> Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Material			
<input type="checkbox"/> Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Process			
<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Fab Site			
<input type="checkbox"/> Mechanical Specification	<input checked="" type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Material			
<input checked="" type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Process			

PCN Details

Description of Change:

Texas Instruments is pleased to announce the Qualification of TI Philippines (PHI) as an additional Assembly & Test site for select package devices. Material differences between sites as follows.

	Current Site	Additional Site
Assembly/Test site	HNA	CDAT
Wire diam/type	1.0mil Au	0.8mil Cu
Mount compound	SID#400194	4226215
Mold compound	SID#450207	4222198
Lead finish	NiPdAu	Matte Sn

Reason for Change:

Continuity of supply.

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Impact on Environmental Ratings:

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
<input checked="" type="checkbox"/> No Change			

Changes to product identification resulting from this PCN:

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (21L)	Assembly City
Hana Semiconductor	HNT	THA	Ayutthaya
TI Chengdu	CDA	CHN	Chengdu
TI Philippines	PHI	PHL	Baguio City

Sample product shipping label (not actual product label)

 TEXAS INSTRUMENTS MADE IN: Malaysia 2DC: 20: MSL '2 / 260C / 1 YEAR SEAL DT MSL 1 / 235C / UNLIM 03/29/04				(1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY (1T) 7523483S12 (P) (2P) REV: (V) 0033317 (20L) CS0: SHE (21L) CCO:USA (22L) AS0: MLA (23L) AC0: MYS										
OPT: ITEM: 39 LBL: 5A (L)T0:1750														
Product Affected: <table border="1"> <tr> <td>INA186A1QDBVRQ1</td> <td>INA186A3QDBVRQ1</td> <td>INA186A5QDBVRQ1</td> <td colspan="2"></td> </tr> <tr> <td>INA186A2QDBVRQ1</td> <td>INA186A4QDBVRQ1</td> <td>SN1906023DBVRQ1</td> <td colspan="2"></td> </tr> </table>					INA186A1QDBVRQ1	INA186A3QDBVRQ1	INA186A5QDBVRQ1			INA186A2QDBVRQ1	INA186A4QDBVRQ1	SN1906023DBVRQ1		
INA186A1QDBVRQ1	INA186A3QDBVRQ1	INA186A5QDBVRQ1												
INA186A2QDBVRQ1	INA186A4QDBVRQ1	SN1906023DBVRQ1												

Qualification Data

Automotive New Product Qualification Summary (As per AEC-Q100 Rev. J and JEDEC Guidelines)

Approve Date 09-MAY -2025

Product Attributes

Attributes	Qual Device: INA186A1QDBVRQ1	QBS Package Reference: INA186A2QDBVRQ1	QBS Package Reference: INA186A3QDBVRQ1	QBS Package Reference: INA186A4QDBVRQ1	QBS Process Reference: IMUX4651QYVRQ1	QBS Package Reference: IMUX4652QYVRQ1	QBS Package Reference: DPA4651QYVRQ1	QBS Package Reference: DPA4652QYVRQ1	QBS Package, Process Reference: INA186A1QDBVRQ1	QBS Package, Process Reference: INA186A2QDBVRQ1	QBS Package, Process Reference: INA186A3QDBVRQ1
Automotive Grade Level	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1
Operating Temp Range (C)	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125
Product Function	Signal Chain	Signal Chain	Signal Chain	Signal Chain	Signal Chain	Signal Chain	Signal Chain	Signal Chain	Signal Chain	Signal Chain	Signal Chain
Wafer Fab Supplier	DMOS6	AIIZU	AIIZU	AIIZU	RFAB	RFAB	RFAB	RFAB	DMOS6	DMOS6	DMOS6
Assembly Site	PHI	PHI	PHI	PHI	PHI	PHI	PHI	PHI	PHI	PHI	PHI
Package Group	SOT	SOT	SOT	SOT	SOT	SOT	SOT	SOT	SOT	SOT	SOT
Package Designator	DBV	DDF	DDF	DDF	DYY	DYY	DYY	DDF	DDF	DDF	DDF
Pin Count	5	8	8	8	16	16	14	8	8	8	8

QBS: Qual By Similarity, also known as Generic Data

Qual Device [INA186A1QDBVRQ1](#) is qualified at MSL1 260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Spec	Test Name	Condition	Duration	Qual Device: INA186A1QDBVRQ1	QBS Package Reference: INA186A2QDBVRQ1	QBS Package Reference: INA186A3QDBVRQ1	QBS Package Reference: INA241ASQD0ER01	QBS Process Reference: IMUX4651QYVRQ1	QBS Package Reference: IMUX4652QYVRQ1	QBS Package Reference: DPA4651QYVRQ1	QBS Package Reference: DPA4652QYVRQ1	QBS Package, Process Reference: INA186A1QDBVRQ1	QBS Package, Process Reference: INA186A2QDBVRQ1	QBS Package, Process Reference: INA186A3QDBVRQ1
Test Group A - Accelerated Environment Stress Tests																
PC	A1	JEDEC J-STD-020 JEDEC A113	Preconditioning	MSL1 260C	-	-	1/0/0	1/0/0	1/0/0	1/0/0	2/0/0	3/0/0	1/308/0 ¹	1/276/0	1/276/0	1/276/0
HAST	A2	JEDEC JESD22- A110	Biased HAST	110C/85%RH	264 Hours	-	-	-	-	-	-	3/231/0	-	-	-	-
HAST	A2	JEDEC JESD22- A110	Biased HAST	130C/85%RH	86 Hours	-	1/77/0	1/77/0	1/77/0	1/77/0	2/154/0	-	1/77/0	1/77/0	1/77/0	1/77/0
ACU/HAST	A3	JEDEC JESD22- A102/DEC JESD22- A118	Autoclave	121C/15psig	86 Hours	-	-	-	-	-	-	3/231/0	-	-	-	-
ACU/HAST	A3	JEDEC JESD22- A102/DEC JESD22- A118	Unbiased HAST	130C/85%RH	86 Hours	-	1/77/0	1/77/0	1/77/0	1/77/0	2/154/0	-	1/77/0	1/77/0	1/77/0	1/77/0
TC	A4	JEDEC JESD22- A104 and Appendix 3	Temperature Cycle	-65C/150C	500 Cycles	-	1/77/0	1/77/0	1/77/0	1/77/0	2/154/0	3/231/0	1/77/0	1/77/0	1/77/0	1/77/0
TC-BP	A4	MIL-STD883 Method 2011	Post Temp Cycle Bond Pull	-	-	-	1/5/0	1/5/0	1/5/0	-	-	-	1/5/0	1/5/0	1/5/0	1/5/0

HTSL	A6	JEDEC JESD22-A103	High Temperature Storage Life	150C	1000 Hours	-	1/450	1/450	1/450	1/450	2900	3/135/0	-	1/450	1/450	1/450
HTSL	A6	JEDEC JESD22-A103	High Temperature Storage Life	175C	500 Hours	-	-	-	-	-	-	-	1/77/0	-	-	-
ESD	B5	-	ESD CDM	-	1500 Volts	-	-	-	-	-	-	1/3/0	-	1/3/0	1/3/0	1/3/0
ESD	B5	-	ESD CDM	-	500 Volts	-	1/3/0	1/3/0	1/3/0	-	-	-	1/3/0	-	-	-
ESD	B5	-	ESD CDM	-	750 Volts	-	-	-	-	-	-	-	-	-	-	-
ESD	B5	-	ESD HBM	-	2000 Volts	-	1/3/0	1/3/0	1/3/0	-	-	-	1/3/0	-	-	-
ESD	B5	-	ESD HBM	-	4000 Volts	-	-	-	-	-	-	1/3/0	-	1/3/0	1/3/0	1/3/0
LU	B7	-	Latch-Up	Per JESD78	-	-	1/6/0	1/6/0	-	-	1/6/0	1/6/0	1/6/0	1/6/0	1/6/0	1/6/0
Test Group B - Accelerated Lifetime Simulation Tests																
HTOL	B1	JEDEC JESD22-A108	Life Test	125C	1000 Hours	-	1/77/0	1/77/0	1/77/0	-	-	-	-	-	-	-
HTOL	B1	JEDEC JESD22-A108	Life Test	150C	300 Hours	-	-	-	-	-	-	-	1/77/0	1/77/0	1/77/0	1/77/0
HTOL	B1	JEDEC JESD22-A109	Life Test	150C	408 Hours	-	-	-	-	-	-	-	1/77/0	-	-	-
ELFR	B2	AEC Q100-008	Early Life Failure Rate	125C	48 Hours	-	-	-	-	-	-	-	-	-	-	-
EDR	B3	AEC Q100-005	NVM Endurance, Data Retention, and Op Life	Per QSS-009-018	1 Step	-	1/77/0	1/77/0	1/77/0	-	-	-	-	-	-	-
Test Group C - Package Assembly Integrity Tests																
WBS	C1	AEC Q100-001	Wire Bond Shear	Minimum of 5 devices, 30 wires, Cpk>1.67	Wires	1/30/0	1/30/0	1/30/0	1/30/0	2/6/0	3/90/0	1/30/0	1/30/0	1/30/0	1/30/0	1/30/0
WBP	C2	MIL-STD883 Method 2011	Wire Bond Pull	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	1/30/0	1/30/0	1/30/0	1/30/0	1/30/0	2/6/0	3/90/0	1/30/0	1/30/0	1/30/0	1/30/0
SD	C3	JEDEC J-STD-002	PB Solderability	>95% Lead Coverage	-	-	1/15/0	1/15/0	1/15/0	-	-	1/15/0	1/15/0	1/15/0	1/15/0	1/15/0
SD	C3	JEDEC J-STD-002	PB-Free Solderability	>95% Lead Coverage	-	-	1/15/0	1/15/0	1/15/0	-	-	1/15/0	1/15/0	1/15/0	1/15/0	1/15/0
PD	C4	JEDEC J-STD-002-B100 and B108	Physical Dimensions	Cpk>1.67	-	1/10/0	1/10/0	1/10/0	1/10/0	1/10/0	2/2/0	3/30/0	1/10/0	1/10/0	1/10/0	1/10/0
Test Group D - Die Fabrication Reliability Tests																
EM	D1	JESD61	Electromigration	-	-	Completed Per Process Technology Requirements										
TDDB	D2	JESD35	Time Dependent Dielectric Breakdown	-	-	Completed Per Process Technology Requirements										
HCI	D3	JESD60 & 28	Hot Carrier Injection	-	-	Completed Per Process Technology Requirements										
BTI	D4	-	Bias Temperature Instability	-	-	Completed Per Process Technology Requirements										
SM	D5	-	Stress Migration	-	-	Completed Per Process Technology Requirements										
Test Group E - Electrical Verification Tests																
ESD	E2	AEC Q100-002	ESD HBM	-	2000 Volts	-	1/3/0	1/3/0	1/3/0	-	-	-	1/3/0	-	-	-
ESD	E2	AEC Q100-002	ESD HBM	-	4000 Volts	-	-	-	-	-	-	-	1/3/0	1/3/0	1/3/0	1/3/0
ESD	E3	AEC Q100-011	ESD CDM	-	1500 Volts	-	-	-	-	-	-	-	1/3/0	-	1/3/0	1/3/0
ESD	E3	AEC Q100-011	ESD CDM	-	500 Volts	-	1/3/0	1/3/0	1/3/0	-	-	-	1/3/0	-	-	-
LU	E4	AEC Q100-004	Latch-Up	Per AEC Q100-004	-	-	1/6/0	1/6/0	1/6/0	-	-	-	1/6/0	1/6/0	1/6/0	1/6/0
ED	E5	AEC Q100-009	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	1/30/0	1/30/0	1/30/0	-	-	-	3/90/0	3/90/0	1/30/0	1/30/0
Additional Tests																
PD	C1	-	Physical Dimensions	Cpk>1.67	-	1/10/0	1/10/0	1/10/0	1/10/0	1/10/0	2/2/0	3/30/0	1/10/0	1/10/0	1/10/0	1/10/0

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Ambient Operating Temperature by Automotive Grade Level:

Grade 0 (or E): -40C to +150C

Grade 1 (or Q): -40C to +125C

Grade 2 (or T): -40C to +105C

Grade 3 (or I) : -40C to +85C

E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):

Room/Hot/Cold : HTOL, ED

Room/Hot : THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU

Room : AC/uHAST

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com>

TI Qualification ID: R-CHG-2504-068

[1]-Precon unit 38 for HTSL lot was lost during precon. HTSL completed with 84 units.

[2]-1 Failure CMRR Hot. Incomplete deep trench etching.

Qualification Data
Automotive Qualification Summary
(As per AEC and JEDEC Guidelines)

Q006 SOT at PHI
 Approve Date 09-May-2025

Product Attributes

Attributes		Q006 Package Reference: <u>INA241A2QDDFRQ1</u> <u>INA241A3QDDFRQ1</u> <u>INA241A5QDDFRQ1</u>	Q006 Package Reference: <u>TMUX4051DYYRQ1</u> <u>TMUX4052DYYRQ11</u>	Q006 Package Reference: <u>OPA4991QDYYRQ1</u>
Automotive Grade Level		Grade 1	Grade 1	Grade 1
Operating Temp Range (C)		-40 to 125	-40 to 125	-40 to 125
Product Function		Signal Chain	Signal Chain	Signal Chain
Wafer Fab Supplier		AIZU	RFAB	RFAB
Assembly Site		PHI	PHI	PHI
Package Group		SOT	SOT	SOT
Package Designator		DDF	DYY	DYY
Pin Count		8	16	14

Qualification Results
 Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Q006 Package Reference: <u>INA241A2QDDFRQ1</u> <u>INA241A3QDDFRQ1</u> <u>INA241A5QDDFRQ1</u>	Q006 Package Reference: <u>TMUX4051DYYRQ1</u> <u>TMUX4052DYYRQ1</u>	Q006 Package Reference: <u>OPA4991QDYYRQ1</u>
Test Group A - Accelerated Environment Stress Tests										
PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Preconditioning	MSL1 260C	-	3/Pass	3/Pass	3/Pass
PC	A1.1	-	3	22	SAM Precon Pre	Review for delamination	-	3/66/0	3/66/0	3/66/0
PC	A1.2	-	3	22	SAM Precon Post	Review for delamination	-	3/66/0	3/66/0	3/66/0
HAST	A2.1	JEDEC JESD22-A110	3	77	Biased HAST	110C/85%RH	264 Hours	-	-	3/231/0
HAST	A2.1	JEDEC JESD22-A110	3	77	Biased HAST	130C/85%RH	96 Hours	3/231/0	3/231/0	-
HAST	A2.1.2	-	3	1	Cross Section, post bHAST, 1X	Post stress cross section	Completed	3/3/0	3/3/0	3/3/0
HAST	A2.1.3	-	3	3	Wire Bond Shear, post bHAST, 1X	Post stress	-	3/9/0	3/9/0	3/9/0
HAST	A2.1.4	-	3	3	Bond Pull over Stitch, post bHAST, 1X	Post stress	-	3/9/0	3/9/0	3/9/0
HAST	A2.1.5	-	3	3	Bond Pull over Ball, post bHAST, 1X	Post stress	-	3/9/0	3/9/0	3/9/0
HAST	A2.2	JEDEC JESD22-A110	3	70	Biased HAST	110C/85%RH	528 Hours	-	-	3/210/0
HAST	A2.2	JEDEC JESD22-A110	3	70	Biased HAST	130C/85%RH	192 Hours	3/210/0	3/210/0	-

HAST	A2.2.1	-	3	22	SAM Analysis, post bHAST 2X	Review for delamination	Completed	3/66/0	3/66/0	3/66/0
HAST	A2.2.2	-	3	1	Cross Section, post bHAST, 2X	Post stress cross section	Completed	3/3/0	3/3/0	3/3/0
HAST	A2.2.3	-	3	3	Wire Bond Shear, post bHAST, 2X	Post stress	-	3/9/0	3/9/0	3/9/0
HAST	A2.2.4	-	3	3	Bond Pull over Stitch, post bHAST, 2X	Post stress	-	3/9/0	3/9/0	3/9/0
HAST	A2.2.5	-	3	3	Bond Pull over Ball, post bHAST, 2X	Post stress	-	3/9/0	3/9/0	3/9/0
TC	A4.1	JEDEC JESD22-A104 and Appendix 3	3	77	Temperature Cycle	-65C/150C	500 Cycles	3/231/0	3/231/0	3/231/0
TC	A4.1.1	-	3	22	SAM Analysis, post TC 1X	Review for delamination	Completed	3/66/0	3/66/0	3/66/0
TC	A4.1.2	-	3	1	Cross Section, post TC, 1X	Post stress cross section	Completed	3/3/0	3/3/0	3/3/0
TC	A4.1.3	-	3	3	Wire Bond Shear, post TC, 1X	Post stress	-	3/9/0	3/9/0	3/9/0
TC	A4.1.4	-	3	3	Bond Pull over Stitch, post TC, 1X	Post stress	-	3/9/0	3/9/0	3/9/0
TC	A4.1.5	-	3	3	Bond Pull over Ball, post TC, 1X	Post stress	-	3/9/0	3/9/0	3/9/0
TC	A4.2	JEDEC JESD22-A104 and Appendix 3	3	70	Temperature Cycle	-65C/150C	1000 Cycles	3/210/0	3/210/0	3/210/0
TC	A4.2.1	-	3	22	SAM Analysis, post TC, 2X	Review for delamination	Completed	3/66/0	3/66/0	3/66/0
TC	A4.2.2	-	3	1	Cross Section, post TC, 2X	Post stress cross section	Completed	3/3/0	3/3/0	3/3/0
TC	A4.2.3	-	3	3	Wire Bond Shear, post TC, 2X	Post stress	-	3/9/0	3/9/0	3/9/0
TC	A4.2.4	-	3	3	Bond Pull over Stitch, post TC, 2X	Post stress	-	3/9/0	3/9/0	3/9/0
TC	A4.2.5	-	3	3	Bond Pull over Ball, post TC, 2X	Post stress	-	3/9/0	3/9/0	3/9/0
HTSL	A6.1	JEDEC JESD22-A103	3	45	High Temperature Storage Life	150C	1000 Hours	3/135/0	3/135/0	3/135/0
HTSL	A6.1.1	-	3	1	Cross Section, post HTSL, 1X	Post stress cross section	Completed	3/3/0	3/3/0	3/3/0
HTSL	A6.2	JEDEC JESD22-A103	3	44	High Temperature Storage Life	150C	2000 Hours	3/132/0	3/132/0	3/132/0
HTSL	A6.2.1	-	3	1	Cross Section, post HTSL, 2X	Post stress cross section	Completed	3/3/0	3/3/0	3/3/0
Test Group C - Package Assembly Integrity Tests										
WBS	C1	AEC Q100-001	1	30	Wire Bond Shear	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	3/90/0	3/90/0	3/90/0
WBP	C2	MIL-STD883 Method 2011	1	30	Wire Bond Pull	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	3/90/0	3/90/0	3/90/0

This report represents AEC-Q006 7.1 Family Data Usage using technology driver and lead products that are most representative of the technology family.

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Ambient Operating Temperature by Automotive Grade Level:

Grade 0 (or E): -40C to +150C

Grade 1 (or Q): -40C to +125C

Grade 2 (or T): -40C to +105C

Grade 3 (or I) : -40C to +85C

E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):

Room/Hot/Cold : HTOL, ED

Room/Hot : THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU

Room : AC/uHAST

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2504-068

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

ZVEI ID: SEM-PA-18, SEM-PA-08, SEM-PA-07, SEM-PA-11, SEM-PA-05, SEM-TF-01

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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